

RF Power Field Effect Transistors

N-Channel Enhancement-Mode Lateral MOSFETs

Designed for CDMA base station applications with frequencies from 1930 to 1990 MHz. Suitable for CDMA and multicarrier amplifier applications. To be used in Class AB and Class C for PCN - PCS/cellular radio and WLL applications.

- Typical Single-Carrier W-CDMA Performance: $V_{DD} = 28$ Volts, $I_{DQ} = 1000$ mA, $P_{out} = 29$ Watts Avg., Full Frequency Band, 3GPP Test Model 1, 64 DPCH with 50% Clipping, Channel Bandwidth = 3.84 MHz, Input Signal PAR = 7.5 dB @ 0.01% Probability on CCDF.
Power Gain — 17.5 dB
Drain Efficiency — 30%
Device Output Signal PAR — 6.1 dB @ 0.01% Probability on CCDF
ACPR @ 5 MHz Offset — -38 dBc in 3.84 MHz Channel Bandwidth
- Capable of Handling 5:1 VSWR, @ 32 Vdc, 1960 MHz, 100 Watts CW Peak Tuned Output Power
- P_{out} @ 1 dB Compression Point ≥ 100 W CW

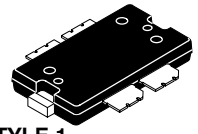
Features

- 100% PAR Tested for Guaranteed Output Power Capability
- Characterized with Series Equivalent Large-Signal Impedance Parameters
- Internally Matched for Ease of Use
- Integrated ESD Protection
- Designed for Digital Predistortion Error Correction Systems
- 200°C Capable Plastic Package
- RoHS Compliant
- In Tape and Reel. R1 Suffix = 500 Units per 44 mm, 13 inch Reel.

MRF7S19100NR1
MRF7S19100NBR1

1930 - 1990 MHz, 29 W AVG., 28 V
SINGLE W-CDMA
LATERAL N-CHANNEL
RF POWER MOSFETs

CASE 1486-03, STYLE 1
TO-270 WB-4
PLASTIC
MRF7S19100NR1



CASE 1484-04, STYLE 1
TO-272 WB-4
PLASTIC
MRF7S19100NBR1

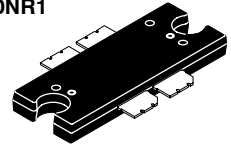


Table 1. Maximum Ratings

Rating	Symbol	Value	Unit
Drain-Source Voltage	V_{DSS}	-0.5, +65	Vdc
Gate-Source Voltage	V_{GS}	-0.5, +10	Vdc
Operating Voltage	V_{DD}	32, +0	Vdc
Storage Temperature Range	T_{stg}	- 65 to +200	°C
Operating Junction Temperature	T_J	200	°C

Table 2. Thermal Characteristics

Characteristic	Symbol	Value ^(1,2)	Unit
Thermal Resistance, Junction to Case	$R_{\theta JC}$		°C/W
Case Temperature 82°C, 100 W CW		0.57	
Case Temperature 79°C, 29 W CW		0.68	

1. MTTF calculator available at <http://www.freescale.com/rf>. Select Tools/Software/Application Software/Calculators to access the MTTF calculators by product.
2. Refer to AN1955, *Thermal Measurement Methodology of RF Power Amplifiers*. Go to <http://www.freescale.com/rf>. Select Documentation/Application Notes - AN1955.

Table 3. ESD Protection Characteristics

Test Methodology	Class
Human Body Model (per JESD22-A114)	1C (Minimum)
Machine Model (per EIA/JESD22-A115)	A (Minimum)
Charge Device Model (per JESD22-C101)	IV (Minimum)

Table 4. Moisture Sensitivity Level

Test Methodology	Rating	Package Peak Temperature	Unit
Per JESD 22-A113, IPC/JEDEC J-STD-020	3	260	°C

Table 5. Electrical Characteristics ($T_C = 25^\circ\text{C}$ unless otherwise noted)

Characteristic	Symbol	Min	Typ	Max	Unit
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Off Characteristics

Zero Gate Voltage Drain Leakage Current ($V_{DS} = 65\text{ Vdc}$, $V_{GS} = 0\text{ Vdc}$)	I_{DSS}	—	—	10	μAdc
Zero Gate Voltage Drain Leakage Current ($V_{DS} = 28\text{ Vdc}$, $V_{GS} = 0\text{ Vdc}$)	I_{DSS}	—	—	1	μAdc
Gate-Source Leakage Current ($V_{GS} = 5\text{ Vdc}$, $V_{DS} = 0\text{ Vdc}$)	I_{GSS}	—	—	500	nAdc

On Characteristics

Gate Threshold Voltage ($V_{DS} = 10\text{ Vdc}$, $I_D = 320\text{ }\mu\text{Adc}$)	$V_{GS(th)}$	1	2	3	Vdc
Gate Quiescent Voltage ⁽¹⁾ ($V_{DS} = 28\text{ Vdc}$, $I_D = 1000\text{ mAdc}$, Measured in Functional Test)	$V_{GS(Q)}$	2	2.8	4	Vdc
Drain-Source On-Voltage ($V_{GS} = 10\text{ Vdc}$, $I_D = 3.2\text{ Adc}$)	$V_{DS(on)}$	0.2	0.24	0.4	Vdc

Dynamic Characteristics ⁽²⁾

Reverse Transfer Capacitance ($V_{DS} = 28\text{ Vdc} \pm 30\text{ mV(rms)ac}$ @ 1 MHz, $V_{GS} = 0\text{ Vdc}$)	C_{rss}	—	1.54	—	pF
Output Capacitance ($V_{DS} = 28\text{ Vdc} \pm 30\text{ mV(rms)ac}$ @ 1 MHz, $V_{GS} = 0\text{ Vdc}$)	C_{oss}	—	553.5	—	pF

Functional Tests (In Freescale Test Fixture, 50 ohm system) $V_{DD} = 28\text{ Vdc}$, $I_{DQ} = 1000\text{ mA}$, $P_{out} = 29\text{ W Avg.}$, $f_1 = 1930\text{ MHz}$, $f_2 = 1990\text{ MHz}$, Single-Carrier W-CDMA, 3GPP Test Model 1, 64 DPCH, 50% Clipping, $PAR = 7.5\text{ dB}$ @ 0.01% Probability on CCDF. ACPR measured in 3.84 MHz Channel Bandwidth @ $\pm 5\text{ MHz}$ Offset.

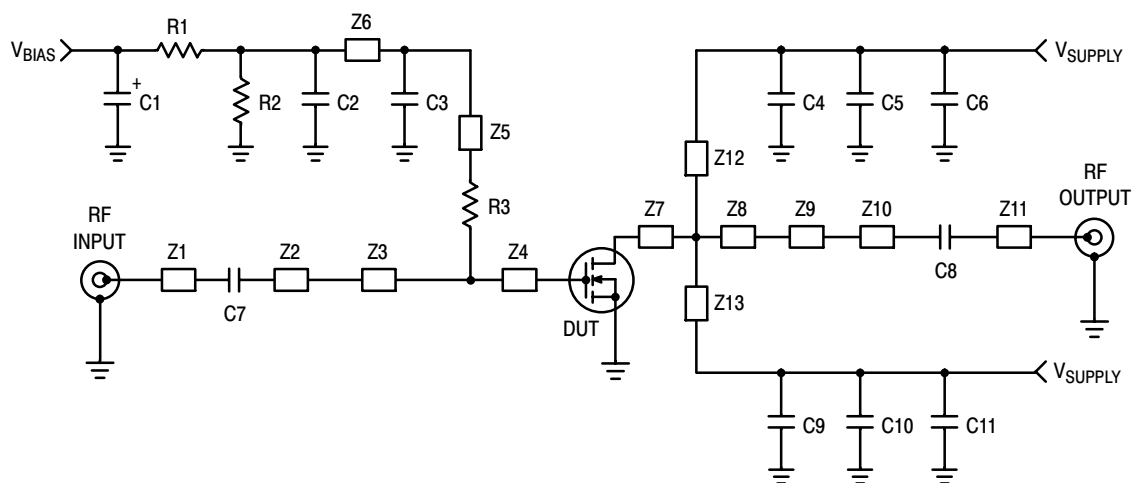
Power Gain	G_{ps}	16.5	17.5	19.5	dB
Drain Efficiency	η_D	28.5	30	—	%
Output Peak-to-Average Ratio @ 0.01% Probability on CCDF	PAR	5.7	6.1	—	dB
Adjacent Channel Power Ratio	ACPR	—	-38	-36	dBc
Input Return Loss	IRL	—	-12	-10	dB

- $V_{GG} = 11/10 \times V_{GS(Q)}$. Parameter measured on Freescale Test Fixture, due to resistive divider network on the board. Refer to Test Circuit schematic.
- Part internally matched both on input and output.

(continued)

Table 5. Electrical Characteristics ($T_C = 25^\circ\text{C}$ unless otherwise noted) (continued)

Characteristic	Symbol	Min	Typ	Max	Unit
Typical Performances (In Freescale Test Fixture, 50 ohm system) $V_{DD} = 28\text{ Vdc}$, $I_{DQ} = 1000\text{ mA}$, 1930-1990 MHz Bandwidth					
Video Bandwidth (Tone Spacing from 100 kHz to VBW) $\Delta\text{IMD3} = \text{IMD3 @ VBW frequency} - \text{IMD3 @ 100 kHz} < 1\text{ dBc}$ (both sidebands)	VBW	—	30	—	MHz
Gain Flatness in 60 MHz Bandwidth @ $P_{out} = 100\text{ W CW}$	G_F	—	1	—	dB
Group Delay @ $P_{out} = 100\text{ W CW}$, $f = 1960\text{ MHz}$	Delay	—	2.15	—	ns
Part-to-Part Insertion Phase Variation @ $P_{out} = 100\text{ W CW}$	$\Delta\Phi$	—	28.8	—	°
Gain Variation over Temperature	ΔG	—	0.019	—	dB/°C
Output Power Variation over Temperature	ΔP_{1dB}	—	0.015	—	dBm/°C



Z1	0.744" x 0.084" Microstrip	Z8	0.319" x 0.880" Microstrip
Z2	0.383" x 0.084" Microstrip	Z9	0.390" x 0.215" Microstrip
Z3	0.600" x 0.230" Microstrip	Z10	0.627" x 0.084" Microstrip
Z4	0.505" x 0.800" Microstrip	Z11	0.743" x 0.084" Microstrip
Z5	1.086" x 0.080" Microstrip	Z12, Z13	1.326" x 0.121" Microstrip
Z6	0.452" x 0.080" Microstrip	PCB	Arlon AD250, 0.030", $\epsilon_r = 2.5$
Z7	0.161" x 0.880" Microstrip		

Figure 1. MRF7S19100NR1(NBR1) Test Circuit Schematic

Table 6. MRF7S19100NR1(NBR1) Test Circuit Component Designations and Values

Part	Description	Part Number	Manufacturer
C1	10 μ F, 35 V Tantalum Capacitor	T491D106K035AT	Kemet
C2, C5, C6, C10, C11	10 μ F, 50 V Chip Capacitors	GRM55DR61H106KA88L	Murata
C3, C7	5.1 pF Chip Capacitors	600B5R1BT250XT	ATC
C4, C9	8.2 pF Chip Capacitors	600B8R2BT250XT	ATC
C8	10 pF Chip Capacitor	600B100BT250XT	ATC
R1	1 K Ω , 1/4 W Chip Resistor	CRCW12061001F100	Vishay
R2	10 K Ω , 1/4 W Chip Resistor	CRCW12061002F100	Vishay
R3	10 Ω , 1/4 W Chip Resistor	CRCW120610R0F100	Vishay

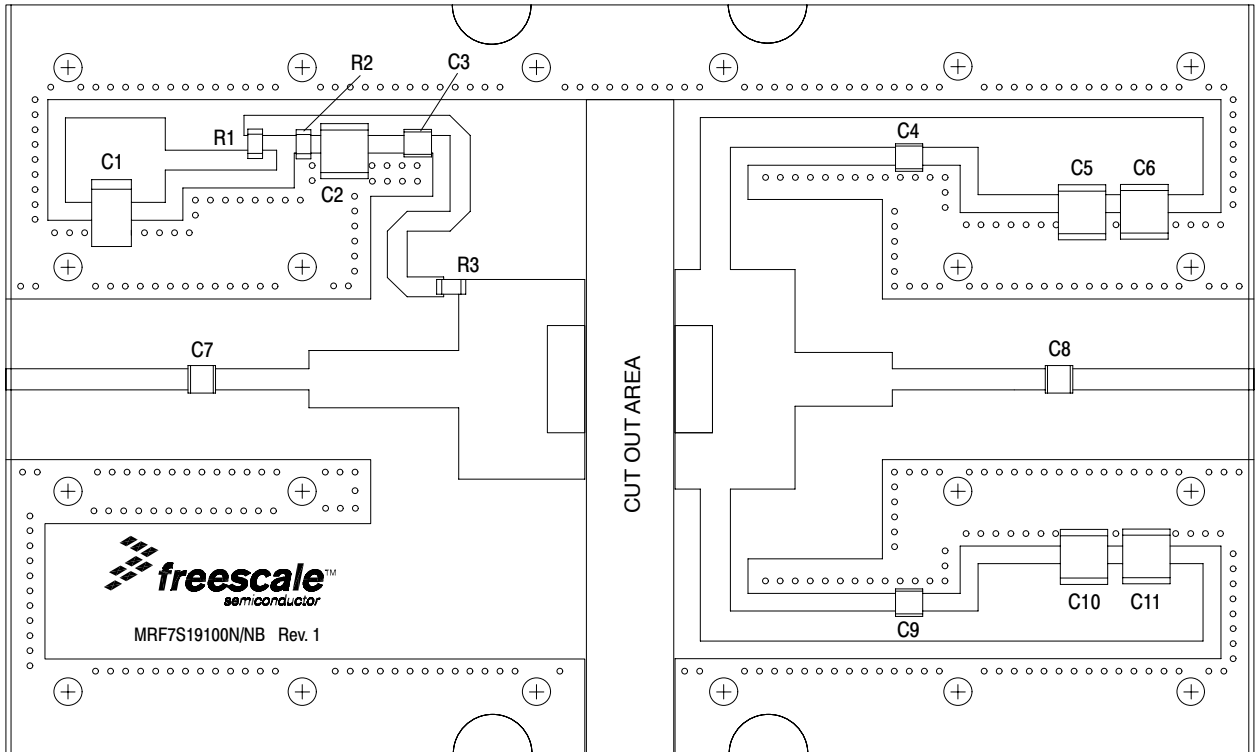
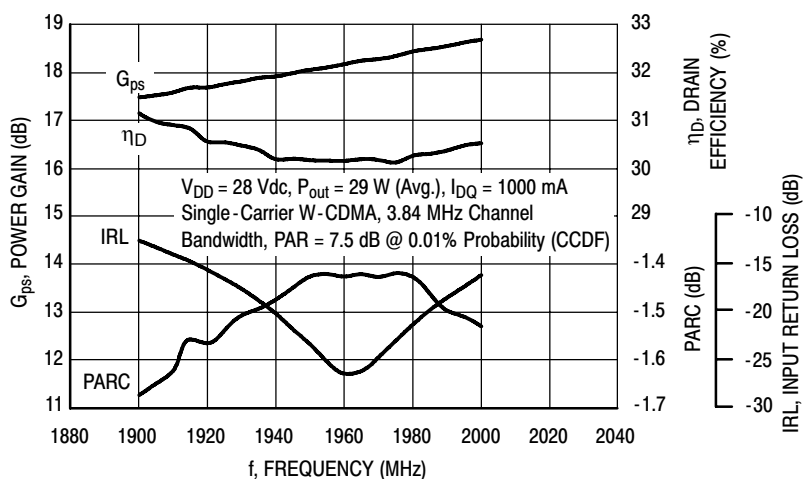
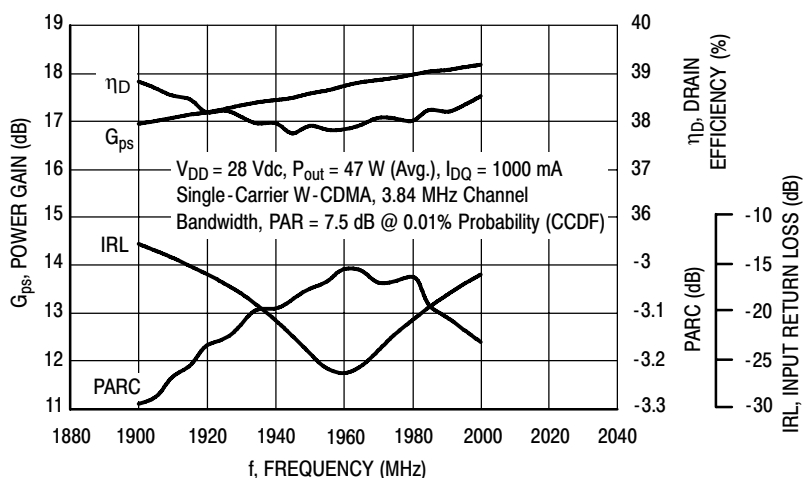


Figure 2. MRF7S19100NR1(NBR1) Test Circuit Component Layout

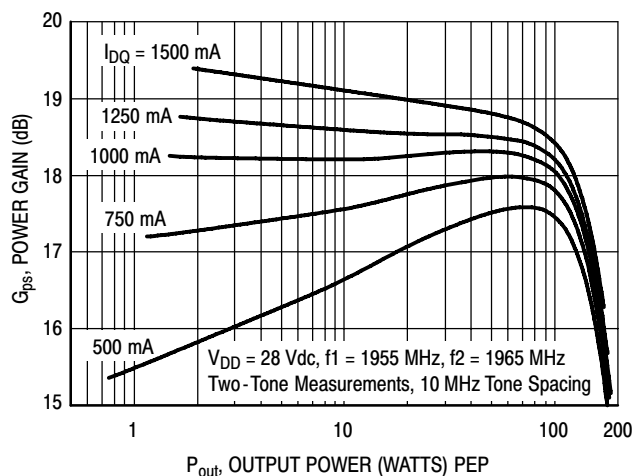
TYPICAL CHARACTERISTICS



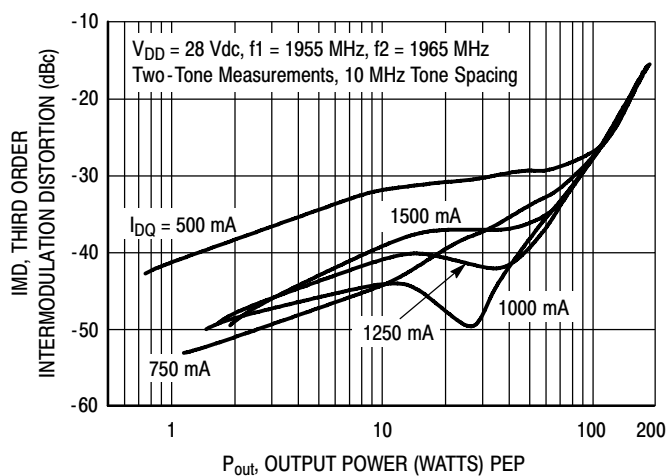
**Figure 3. Output Peak-to-Average Ratio Compression (PARC)
Broadband Performance @ $P_{out} = 29$ Watts Avg.**



**Figure 4. Output Peak-to-Average Ratio Compression (PARC)
Broadband Performance @ $P_{out} = 47$ Watts Avg.**



**Figure 5. Two-Tone Power Gain versus
Output Power**



**Figure 6. Third Order Intermodulation Distortion
versus Output Power**

TYPICAL CHARACTERISTICS

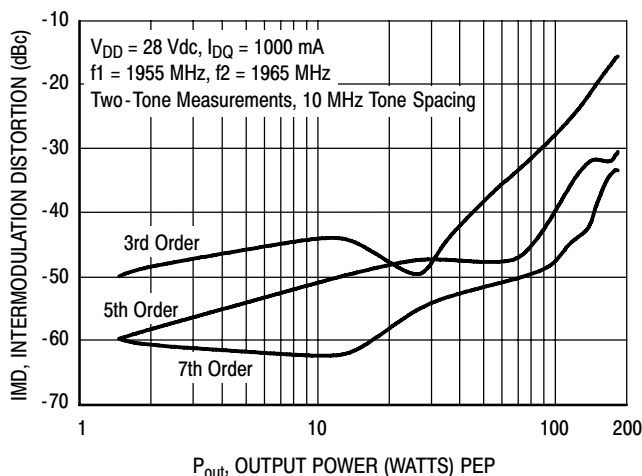


Figure 7. Intermodulation Distortion Products versus Output Power

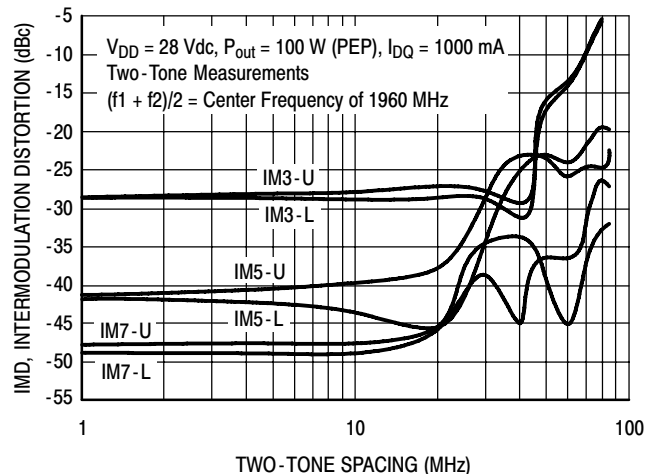


Figure 8. Intermodulation Distortion Products versus Tone Spacing

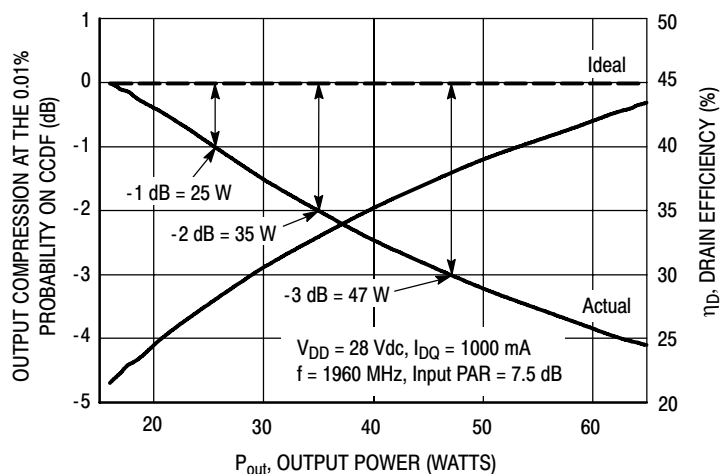


Figure 9. Output Peak-to-Average Ratio Compression (PARC) versus Output Power

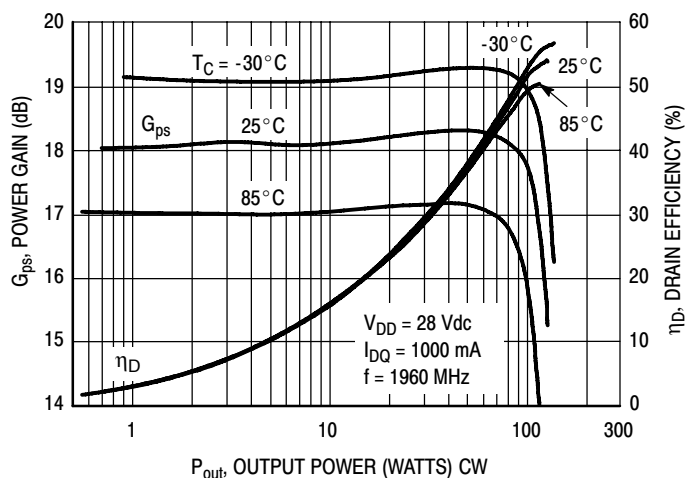


Figure 10. Power Gain and Drain Efficiency versus CW Output Power

MRF7S19100NR1 MRF7S19100NBR1

TYPICAL CHARACTERISTICS

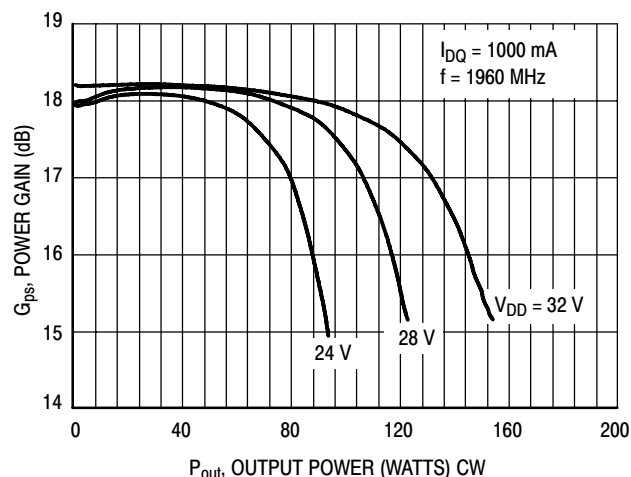
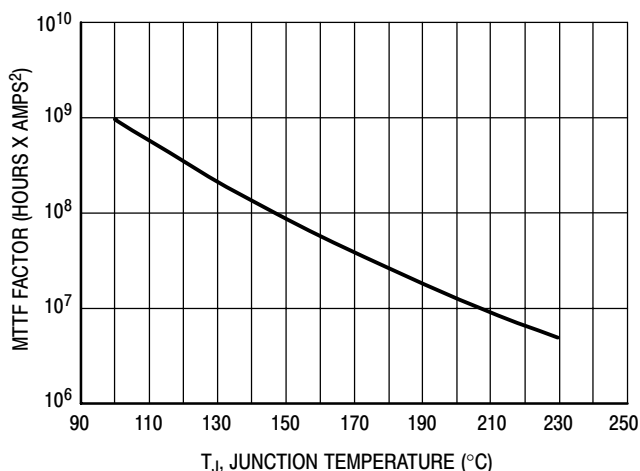


Figure 11. Power Gain versus Output Power



This above graph displays calculated MTTF in hours x ampere² drain current. Life tests at elevated temperatures have correlated to better than $\pm 10\%$ of the theoretical prediction for metal failure. Divide MTTF factor by I_D^2 for MTTF in a particular application.

Figure 12. MTTF Factor versus Junction Temperature

W-CDMA TEST SIGNAL

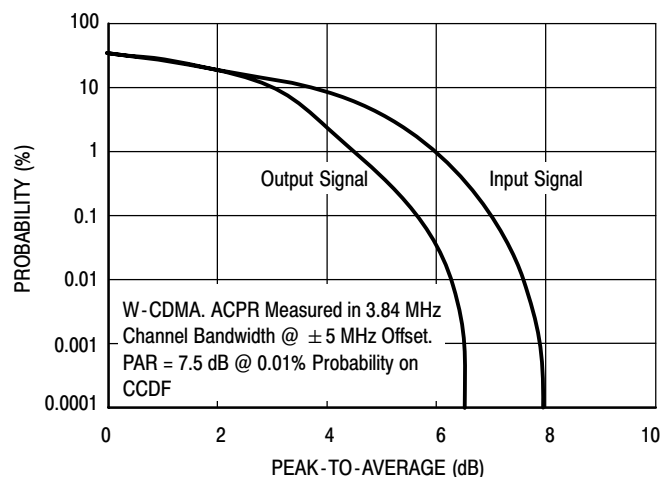


Figure 13. CCDF W-CDMA 3GPP, Test Model 1, 64 DPCH, 50% Clipping, Single-Carrier Test Signal

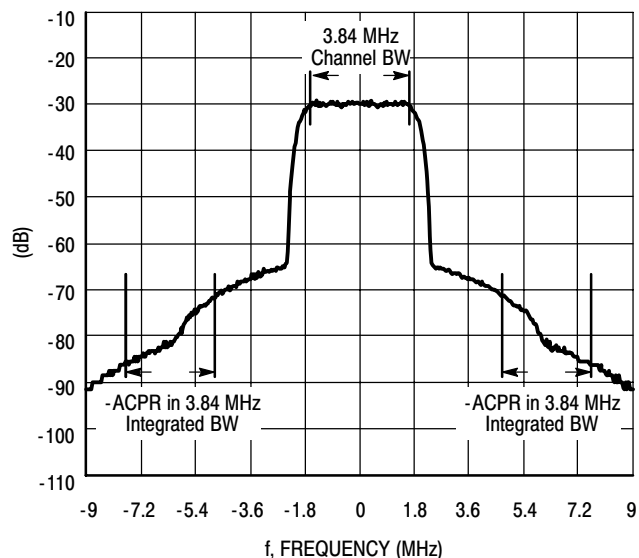
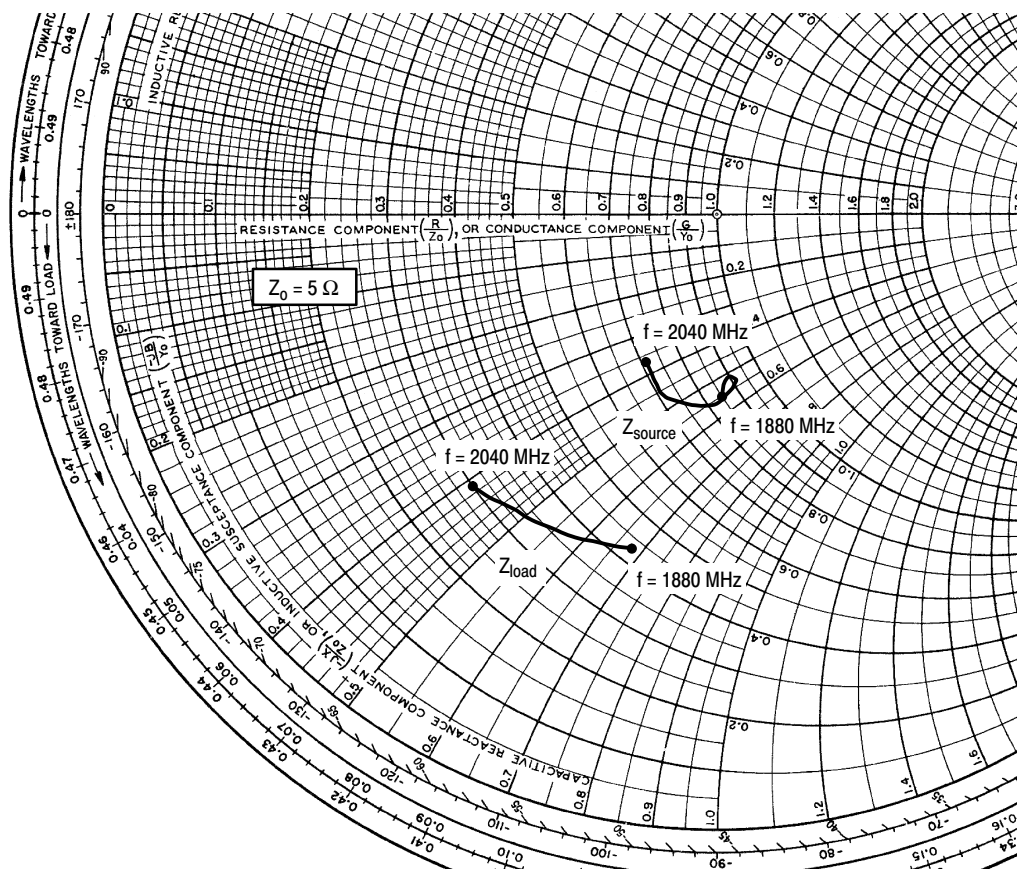


Figure 14. Single-Carrier W-CDMA Spectrum



$V_{DD} = 28 \text{ Vdc}$, $I_{DQ} = 1000 \text{ mA}$, $P_{out} = 29 \text{ W Avg.}$

f MHz	Z_{source} Ω	Z_{load} Ω
1880	$4.257 - j2.758$	$2.143 - j3.408$
1900	$4.388 - j2.617$	$2.038 - j3.236$
1920	$4.521 - j2.560$	$1.944 - j3.066$
1940	$4.568 - j2.630$	$1.858 - j2.898$
1960	$4.424 - j2.758$	$1.775 - j2.725$
1980	$4.124 - j2.800$	$1.708 - j2.550$
2000	$3.819 - j2.611$	$1.643 - j2.387$
2020	$3.567 - j2.292$	$1.572 - j2.223$
2040	$3.525 - j1.844$	$1.487 - j2.029$

Z_{source} = Test circuit impedance as measured from gate to ground.

Z_{load} = Test circuit impedance as measured from drain to ground.

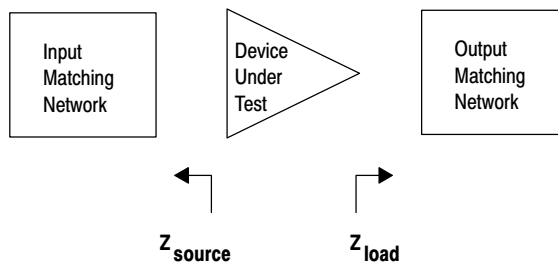
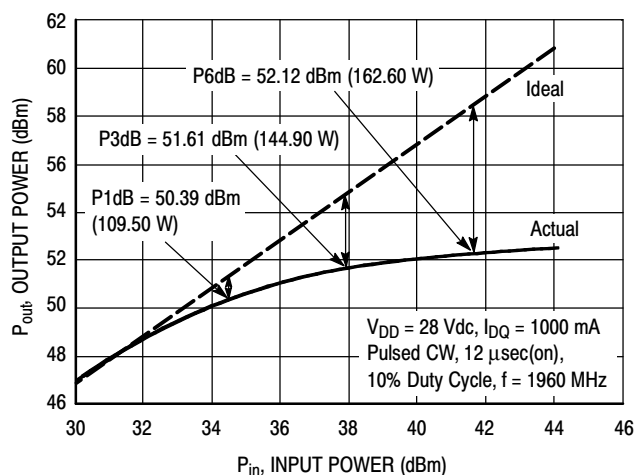


Figure 15. Series Equivalent Source and Load Impedance

ALTERNATIVE PEAK TUNE LOAD PULL CHARACTERISTICS

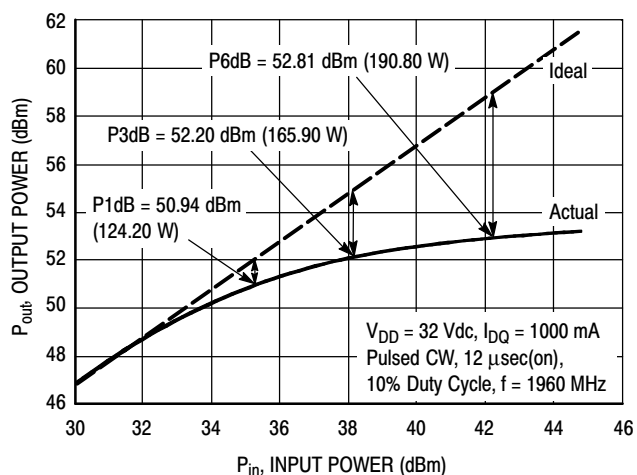


NOTE: Measured in a Peak Tuned Load Pull Fixture

Test Impedances per Compression Level

	Z_{source} Ω	Z_{load} Ω
P3dB	4.39 - j5.66	1.81 - j3.27

Figure 16. Pulsed CW Output Power versus Input Power



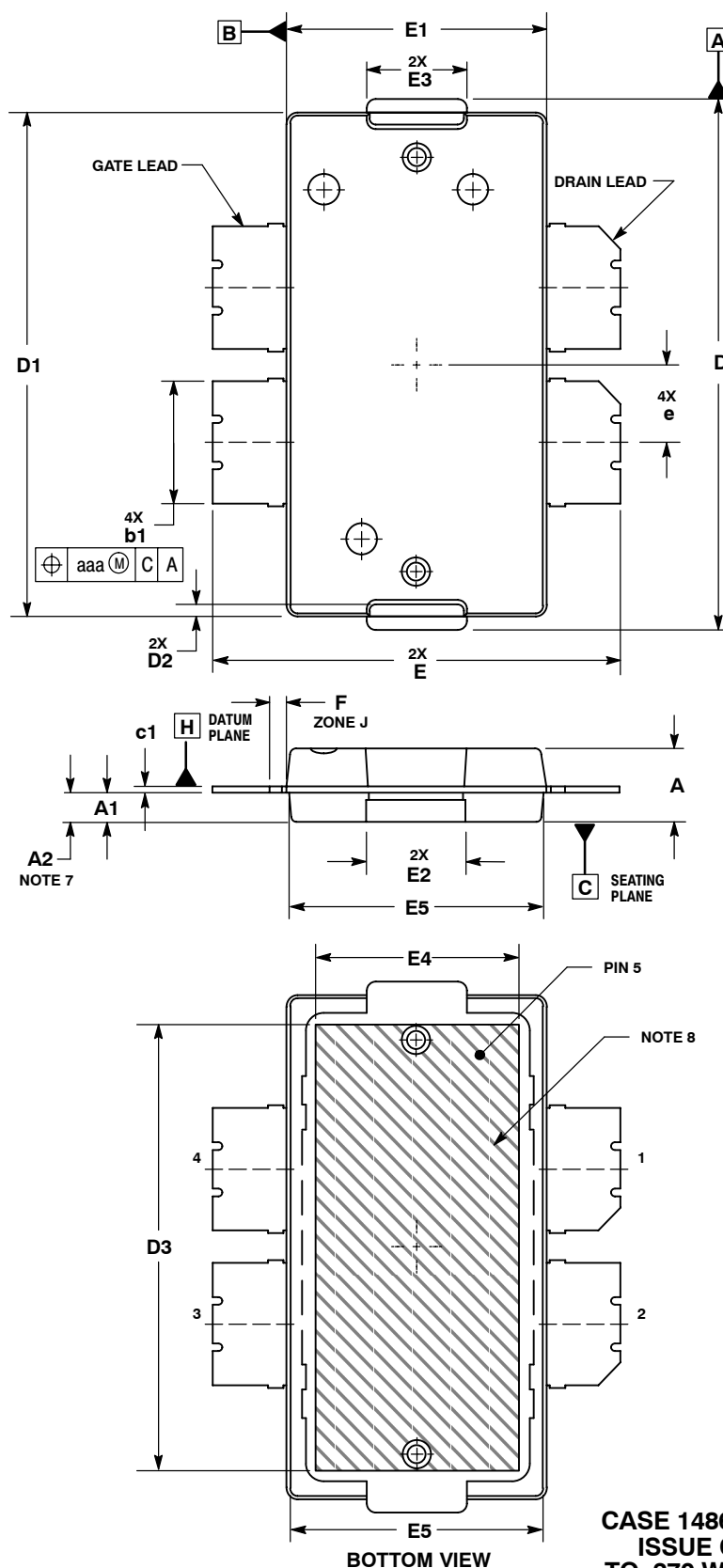
NOTE: Measured in a Peak Tuned Load Pull Fixture

Test Impedances per Compression Level

	Z_{source} Ω	Z_{load} Ω
P3dB	4.39 - j5.66	1.81 - j3.27

Figure 17. Pulsed CW Output Power versus Input Power

PACKAGE DIMENSIONS



NOTES:

1. CONTROLLING DIMENSION: INCH.
2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M-1994.
3. DATUM PLANE -H- IS LOCATED AT THE TOP OF LEAD AND IS COINCIDENT WITH THE LEAD WHERE THE LEAD EXITS THE PLASTIC BODY AT THE TOP OF THE PARTING LINE.
4. DIMENSIONS "D" AND "E1" DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS .006 PER SIDE. DIMENSIONS "D" AND "E1" DO INCLUDE MOLD MISMATCH AND ARE DETERMINED AT DATUM PLANE -H-.
5. DIMENSION "b1" DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE .005 TOTAL IN EXCESS OF THE "b1" DIMENSION AT MAXIMUM MATERIAL CONDITION.
6. DATUMS -A- AND -B- TO BE DETERMINED AT DATUM PLANE -H-.
7. DIMENSION A2 APPLIES WITHIN ZONE "J" ONLY.
8. HATCHING REPRESENTS THE EXPOSED AREA OF THE HEAT SLUG.

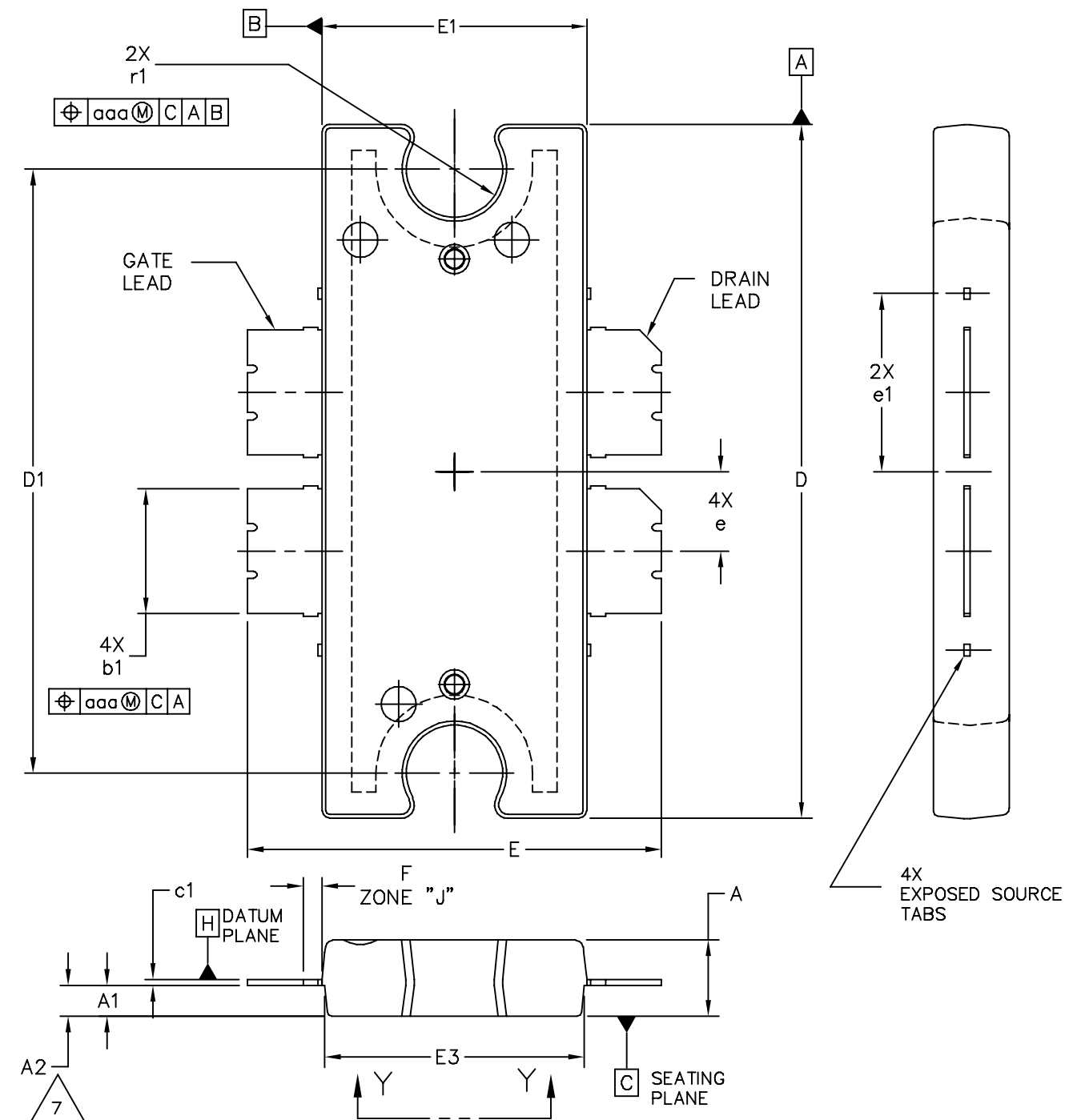
DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	.100	.104	2.54	2.64
A1	.039	.043	0.99	1.09
A2	.040	.042	1.02	1.07
D	.712	.720	18.08	18.29
D1	.688	.692	17.48	17.58
D2	.011	.019	0.28	0.48
D3	.600	---	15.24	---
E	.551	.559	14	14.2
E1	.353	.357	8.97	9.07
E2	.132	.140	3.35	3.56
E3	.124	.132	3.15	3.35
E4	.270	---	6.86	---
E5	.346	.350	8.79	8.89
F	.025 BSC		0.64 BSC	
b1	.164	.170	4.17	4.32
c1	.007	.011	0.18	0.28
e	.106 BSC		2.69 BSC	
aaa	.004		0.10	

STYLE 1:

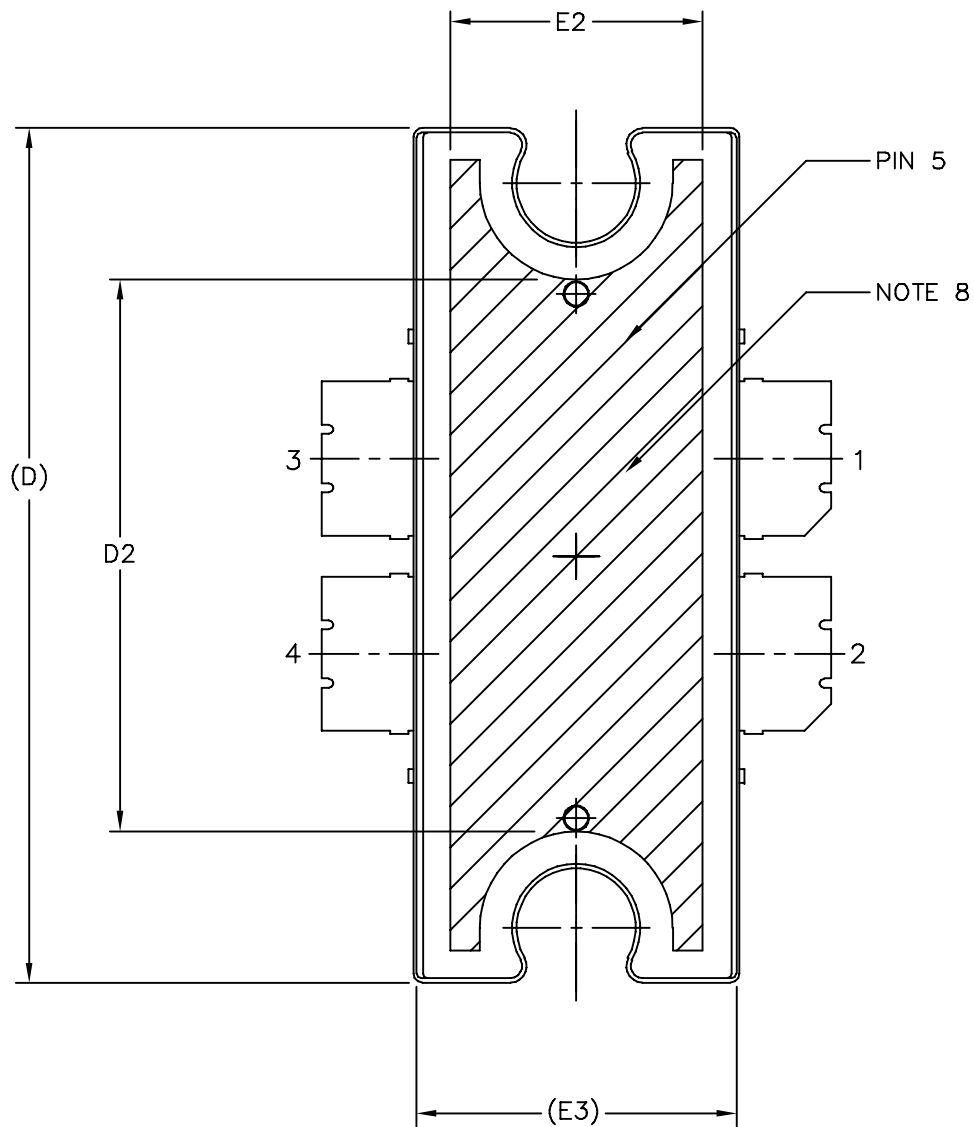
- PIN 1. DRAIN
- DRAIN
- GATE
- GATE
- SOURCE

**CASE 1486-03
ISSUE C
TO-270 WB-4
PLASTIC
MRF7S19100N**

MRF7S19100NR1 MRF7S19100NBR1



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		CASE NUMBER: 1484-04	05 APR 2006
		STANDARD: NON-JEDEC	



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		CASE NUMBER: 1484-04	05 APR 2006
		STANDARD: NON-JEDEC	

MRF7S19100NR1 MRF7S19100NBR1

NOTES:

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4. DIMENSIONS "D" AND "E1" DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS .006 PER SIDE. DIMENSIONS "D" AND "E1" DO INCLUDE MOLD MISMATCH AND ARE DETERMINED AT DATUM PLANE H.
5. DIMENSIONS "b1" DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE .005 TOTAL IN EXCESS OF THE "b1" DIMENSION AT MAXIMUM MATERIAL CONDITION.
6. DATUM A AND B TO BE DETERMINED AT DATUM PLANE H.
7. DIMENSION A2 APPLIES WITHIN ZONE "J" ONLY.
8. HATCHING REPRESENTS EXPOSED AREA OF THE HEAT SLUG. HATCHED AREA SHOWN IS ON THE SAME PLANE.

STYLE 1:

PIN 1 - DRAIN PIN 2 - DRAIN
PIN 3 - GATE PIN 4 - GATE
PIN 5 - SOURCE

INCH			MILLIMETER		INCH			MILLIMETER	
DIM	MIN	MAX	MIN	MAX	DIM	MIN	MAX	MIN	MAX
A	.100	.104	2.54	2.64	b1	.164	.170	4.17	4.32
A1	.039	.043	0.99	1.09	c1	.007	.011	.18	.28
A2	.040	.042	1.02	1.07	r1	.063	.068	1.60	1.73
D	.928	.932	23.57	23.67	e	.106 BSC		2.69 BSC	
D1	.810 BSC		20.57 BSC		e1	.239 INFO ONLY		6.07 INFO ONLY	
D2	.600	---	15.24	---	aaa	.004		.10	
E	.551	.559	14	14.2					
E1	.353	.357	8.97	9.07					
E2	.270	---	6.86	---					
E3	.346	.350	8.79	8.89					
F	.025 BSC		0.64 BSC						
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					CASE NUMBER: 1484-04			05 APR 2006	
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